AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

- 1. (original): A Group III nitride semiconductor element comprising a substrate; a first nitride semiconductor layer composed of AlN which is provided on the substrate; a second nitride semiconductor layer composed of $Al_{x1}Ga_{1-x1}N$ ($0 \le x1 \le 0.1$) which is provided on the first nitride semiconductor layer; and a third nitride semiconductor layer composed of $Al_{x2}Ga_{1}$. $a_{x2}N$ (0 < x2 < 1 and $x1 + 0.02 \le x2$) which is provided on the second nitride semiconductor layer.
- 2. (original): A Group III nitride semiconductor element according to claim 1, wherein said substrate is selected from a group consisting of sapphire single crystal, Si single crystal, SiC single crystal, AlN single crystal, and GaN single crystal
- 3. (currently amended): A Group III nitride semiconductor element according to claim 1-or-2, wherein said second nitride semiconductor layer is formed of an island-like structure in which crystals of different heights are arranged so as to be separated from one another.
- 4. (currently amended): A Group III nitride semiconductor element according to any one of claims 1 to 3claim 1, wherein said second nitride semiconductor layer contains a region having a low Al content and a region having a high Al content.

- 5. (currently amended): A Group III nitride semiconductor element according to any one of claims 1-to 4claim 1, wherein said second nitride semiconductor layer is composed of $Al_{x1}Ga_{1-x1}N$ ($0 \le x1 \le 0.05$).
- 6. (original): A Group III nitride semiconductor element according to claim 5, wherein said second nitride semiconductor layer is composed of $Al_{x1}Ga_{1-x1}N$ ($0 \le x1 \le 0.02$).
- 7. (currently amended): A Group III nitride semiconductor element according to any one of claims 1 to 6claim 1, wherein said second nitride semiconductor layer has a thickness of 1 to 500 nm.
- 8. (original): A Group III nitride semiconductor element according to claim 7, wherein said second nitride semiconductor layer has a thickness of 1 to 400 nm.
- 9. (original): A Group III nitride semiconductor element according to claim 8, wherein said second nitride semiconductor layer has a thickness of 1 to 300 nm.
- 10. (currently amended): A Group III nitride semiconductor element according to any one of claims 1 to 9claim 1, wherein said second nitride semiconductor layer is composed of an undoped semiconductor.

- 11. (currently amended): A Group III nitride semiconductor light-emitting device comprising a Group III nitride semiconductor element according to any one of claims 1 to 10claim 1; a fourth nitride semiconductor layer provided on said third nitride semiconductor layer of said semiconductor element, said fourth nitride semiconductor layer including an n-type layer, a light-emitting layer, and a p-type layer, which are successively formed atop said third nitride semiconductor layer in this order; a negative electrode provided on said n-type layer; and a positive electrode provided on said p-type layer.
- 12. (original): A light-emitting diode comprising a Group III nitride semiconductor light-emitting device according to claim 11.
- 13. (original): A laser diode comprising a Group III nitride semiconductor lightemitting device according to claim 11.
- 14. (currently amended): A semiconductor device comprising a Group III nitride semiconductor element according to any one of claims 1 to 10claim 1.
- 15. (new): A Group III nitride semiconductor element according to claim 1, wherein said first nitride semiconductor layer has a thickness of 0.005 to 0.5 μm.